

SN65LBC176A, SN75LBC176A DIFFERENTIAL BUS TRANSCEIVERS

SLLS376D– MAY 2000 – REVISED JULY 2008

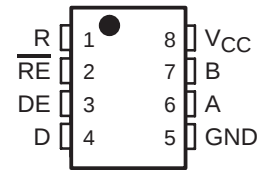
- Designed for Signaling Rates[†] Up to 30 Mbps
- Bus-Pin ESD Protection Exceeds 12 kV HBM
- Compatible With ANSI Standard TIA/EIA-485-A and ISO 8482:1987(E)
- Low Skew
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- Very Low Disabled Supply-Current Requirements . . . 700 μ A Maximum
- Common Mode Voltage Range of –7 V to 12 V
- Thermal-Shutdown Protection
- Driver Positive and Negative Current Limiting
- Open-Circuit Failsafe Receiver Design
- Receiver Input Sensitivity . . . ± 200 mV Max
- Receiver Input Hysteresis . . . 50 mV Typ
- Glitch-Free Power-Up and Power-Down Protection
- Available in Q-Temp Automotive High Reliability Automotive Applications Configuration Control / Print Support Qualification to Automotive Standards

description

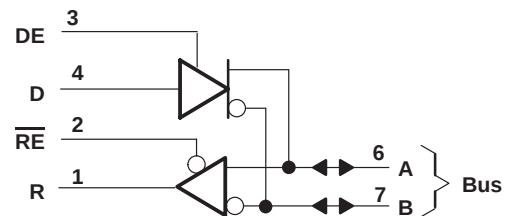
The SN65LBC176A, SN65LBC176AQ, and SN75LBC176A differential bus transceivers are monolithic, integrated circuits designed for bidirectional data communication on multipoint bus-transmission lines. They are designed for balanced transmission lines and are compatible with ANSI standard TIA/EIA-485-A and ISO 8482. The A version offers improved switching performance over its predecessors without sacrificing significantly more power.

SN65LBC176AQD (Marked as B176AQ)
SN65LBC176AD (Marked as BL176A)
SN65LBC176AP (Marked as 65LBC176A)
SN75LBC176AD (Marked as LB176A)
SN75LBC176AP (Marked as 75LBC176A)

(TOP VIEW)



logic diagram (positive logic)



Function Tables

DRIVER

INPUT D	ENABLE DE	OUTPUTS	
		A	B
H	H	H	L
L	H	L	H
X	L	Z	Z
Open	H	H	L

RECEIVER

DIFFERENTIAL INPUTS $V_A - V_B$	ENABLE RE	OUTPUT R
$V_{ID} \geq 0.2$ V	L	H
-0.2 V $< V_{ID} < 0.2$ V	L	?
$V_{ID} \leq -0.2$ V	L	L
X	H	Z
Open	L	H

H = high level, L = low level, ? = indeterminate,
X = irrelevant, Z = high impedance (off)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

[†] Signaling rate by TIA/EIA-485-A definition restrict transition times to 30% of the bit duration, and much higher signaling rates may be achieved using a different criteria (see TYPICAL CHARACTERISTICS section).

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

Copyright © 2000–2008, Texas Instruments Incorporated

SN65LBC176A, SN75LBC176A

DIFFERENTIAL BUS TRANSCEIVERS

SLLS376D– MAY 2000 – REVISED JULY 2008

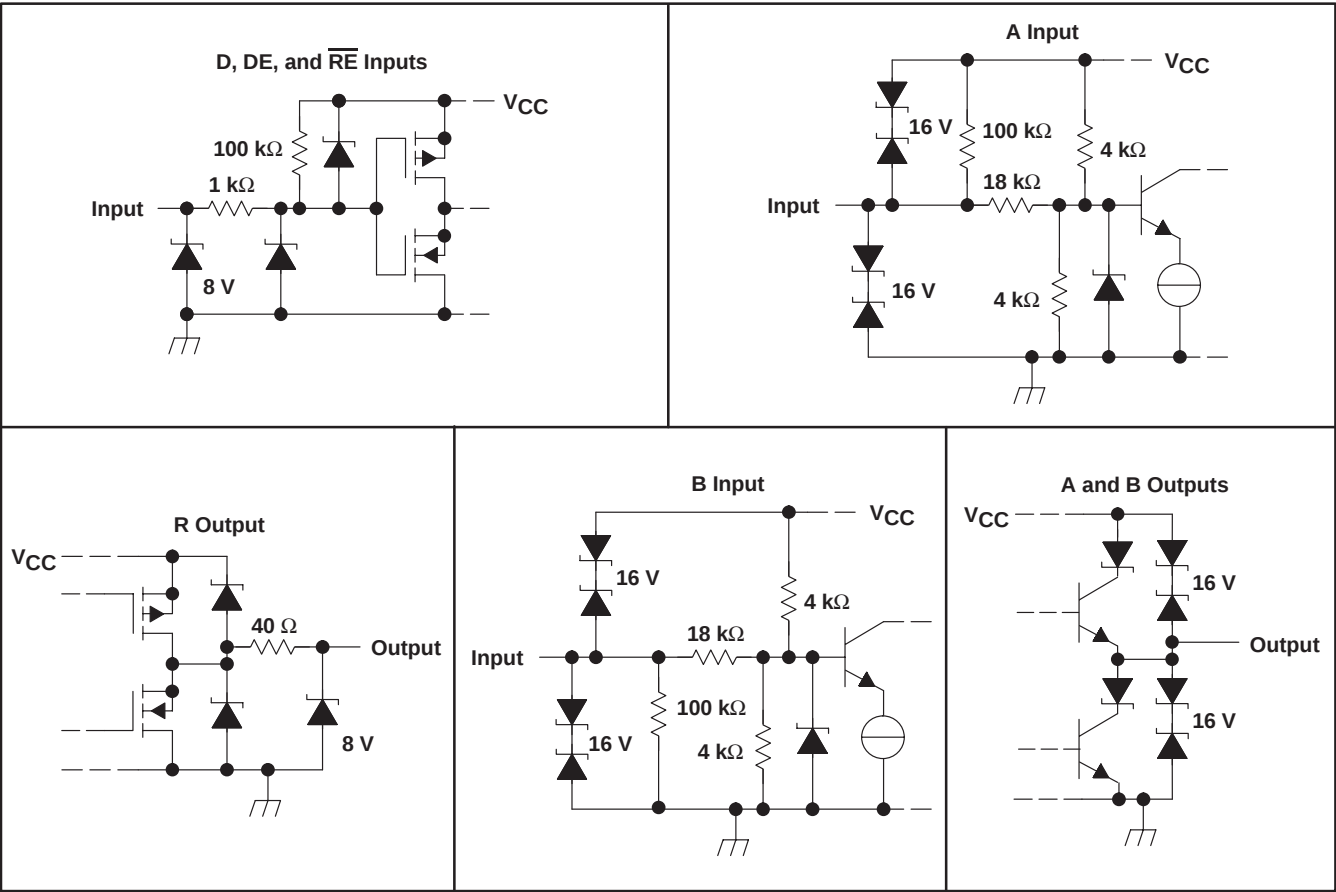
description (continued)

The SN65LBC176A, SN65LBC176AQ, and SN75LBC176A combine a 3-state, differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, which can externally connect together to function as a direction control. The driver differential outputs and the receiver differential inputs connect internally to form a differential input/output (I/O) bus port that is designed to offer minimum loading to the bus whenever the driver is disabled or $V_{CC} = 0$. This port features wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications. Very low device supply current can be achieved by disabling the driver and the receiver.

AVAILABLE OPTIONS

T _A	PACKAGE	
	SMALL OUTLINE (D)	PLASTIC DUAL-IN-LINE
0°C to 70°C	SN75LBC176AD	SN75LBC176AP
–40°C to 85°C	SN65LBC176AD	SN65LBC176AP
–40°C to 125°C	SN65LBC176AQD	—

schematics of inputs and outputs



SN65LBC176A, SN75LBC176A DIFFERENTIAL BUS TRANSCEIVERS

SLLS376D– MAY 2000 – REVISED JULY 2008

absolute maximum ratings[†]

Supply voltage, V_{CC} (see Note 1)	–0.3 V to 6 V
Voltage range at any bus terminal (A or B)	–10 V to 15 V
Input voltage, V_I (D, DE, R, or $\overline{RE}$)	–0.3 V to $V_{CC} + 0.5$ V
Electrostatic discharge: Bus terminals and GND, Class 3, A: (see Note 2)	12 kV
Bus terminals and GND, Class 3, B: (see Note 2)	400 V
All terminals, Class 3, A:	3 kV
All terminals, Class 3, B:	400 V
Continuous total power dissipation (see Note 3)	See Dissipation Rating Table
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.
2. Tested in accordance with MIL–STD–883C, Method 3015.7
3. The maximum operating junction temperature is internally limited. Use the dissipation rating table to operate below this temperature.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR [‡] ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW
P	1000 mW	8.0 mW/°C	640 mW	520 mW	—

[‡] This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
Voltage at any bus terminal (separately or common mode), V_I or V_{IC}		–7		12	V
High-level input voltage, V_{IH}	D, DE, and $\overline{RE}$	2		V_{CC}	V
Low-level input voltage, V_{IL}	D, DE, and $\overline{RE}$	0		0.8	V
Differential input voltage, V_{ID} (see Note 4)		–12 [§]		12	V
High-level output current, I_{OH}	Driver	–60			mA
	Receiver	–8			
Low-level output current, I_{OL}	Driver			60	mA
	Receiver			8	
Operating free-air temperature, T_A	SN65LBC176AQ	–40		125	°C
	SN65LBC176A	–40		85	
	SN75LBC176A	0		70	

[§] The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet.

NOTE 4: Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



SN65LBC176A, SN75LBC176A DIFFERENTIAL BUS TRANSCEIVERS

SLLS376D– MAY 2000 – REVISED JULY 2008

driver electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IK}	Input clamp voltage	I _I = −18 mA		−1.5	−0.8		V
V _{OD}	Differential output voltage	I _O = 0	SN65LBC176AQ	1.5	4	6	V
			SN65LBC176A, SN75LBC176A	4			
		R _L = 54 Ω, See Figure 1	SN65LBC176AQ	0.9	1.5	6	V
			SN65LBC176A	1	1.5	3	
			SN75LBC176A	1.1	1.5	3	
		V _{test} = −7 V to 12 V, See Figure 2	SN65LBC176AQ	0.9	1.5	6	V
			SN65LBC176A	1	1.5	3	
			SN75LBC176A	1.1	1.5	3	
Δ V _{OD}	Change in magnitude of differential output voltage	See Figures 1 and 2			−0.2	0.2	V
V _{OC(SS)}	Steady-state common-mode output voltage	See Figure 1	SN65LBC176AQ	1.8	2.4	3	V
ΔV _{OC(SS)}	Change in steady-state common-mode output voltage		SN65LBC176A, SN75LBC176A	1.8	2.4	2.8	
			SN65LBC176AQ	−0.2 0.2			
			SN65LBC176A, SN75LBC176A	−0.1 0.1			
I _{OZ}	High-impedance output current	See receiver input currents					
I _{IH}	High-level enable input current	V _I = 2 V			−100		μA
I _{IL}	Low-level enable input current	V _I = 0.8 V			−100		μA
I _{OS}	Short-circuit output current	−7 V ≤ V _O ≤ 12 V			−250	250	mA
I _{CC}	Supply current	V _I = 0 or V _{CC} , No load	Receiver disabled and driver enabled	5 9			mA
			Receiver disabled and driver disabled	0.4 0.7			
			Receiver enabled and driver enabled	8.5 15			

† All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

driver switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN65LBC176AQ			SN65LBC176A SN75LBC176A			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
t_{PLH} Propagation delay time, low-to-high-level output	$R_L = 54 \Omega$, $C_L = 50 \text{ pF}$, See Figure 3	2		12	2	6	12	ns
t_{PHL} Propagation delay time, high-to-low-level output		2		12	2	6	12	ns
$t_{sk(p)}$ Pulse skew ($ t_{PLH} - t_{PHL} $)				2		0.3	1	ns
t_r Differential output signal rise time		1.2		11	4	7.5	11	ns
t_f Differential output signal fall time		1.2		11	4	7.5	11	ns
t_{PZH} Propagation delay time, high-impedance-to-high-level output	$R_L = 110 \Omega$, See Figure 4			22		12	22	ns
t_{PZL} Propagation delay time, high-impedance-to-low-level output	$R_L = 110 \Omega$, See Figure 5			25		12	22	ns
t_{PHZ} Propagation delay time, high-level-to-high-impedance output	$R_L = 110 \Omega$, See Figure 4			22		12	22	ns
t_{PLZ} Propagation delay time, low-level-to-high-impedance output	$R_L = 110 \Omega$, See Figure 5			22		12	22	ns

† All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

SN65LBC176A, SN75LBC176A DIFFERENTIAL BUS TRANSCEIVERS

SLLS376D– MAY 2000 – REVISED JULY 2008

receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	I _O = −8 mA			0.2			V
V _{IT−}	Negative-going input threshold voltage	I _O = 8 mA			−0.2			V
V _{hys}	Hysteresis voltage (V _{IT+} − V _{IT−})				50			mV
V _{IK}	Enable-input clamp voltage	I _I = −18 mA			−1.5	−0.8		V
V _{OH}	High-level output voltage	V _{ID} = 200 mV,	I _{OH} = −8 mA,	See Figure 6	4	4.9		V
V _{OL}	Low-level output voltage	V _{ID} = −200 mV,	I _{OL} = 8 mA,	See Figure 6	0.1	0.8		V
I _{OZ}	High-impedance-state output current	V _O = 0 to V _{CC}		SN65LBC176AQ	−10		10	μA
				SN65LBC176A, SN75LBC176A	−1		1	
I _I	Bus input current	V _{IH} = 12 V, V _{CC} = 5 V		Other input at 0 V	0.4		1	mA
		V _{IH} = 12 V, V _{CC} = 0			0.5		1	
		V _{IH} = −7 V, V _{CC} = 5 V			−0.8	−0.4		
		V _{IH} = −7 V, V _{CC} = 0			−0.8	−0.3		
I _{IH}	High-level enable-input current	V _{IH} = 2 V			−100			μA
I _{IL}	Low-level enable-input current	V _{IL} = 0.8 V			−100			μA
I _{CC}	Supply current	V _I = 0 or V _{CC} , No load	Receiver enabled and driver disabled		4		7	mA
			Receiver disabled and driver disabled		0.4		0.7	
			Receiver enabled and driver enabled		8.5		15	

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

receiver switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN65LBC176AQ			SN65LBC176A SN75LBC176A			UNIT
		MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	
t _{PLH} Propagation delay time, output↑	V _{ID} = -1.5 V to 1.5 V, See Figure 7	7		30	7	13	20	ns
t _{PHL} Propagation delay time, output↓		7		30	7	13	20	ns
t _{sk(p)} Pulse skew (t _{PHL} - t _{PLH})				6		0.5	1.5	ns
t _r Rise time, output	See Figure 7			5		2.1	3.3	ns
t _f Fall time, output				5		2.1	3.3	ns
t _{PZH} Output enable time to high level	C _L = 10 pF, See Figure 8			50		30	45	ns
t _{PZL} Output enable time to low level				50		30	45	ns
t _{PHZ} Output disable time from high level				60		20	40	ns
t _{PLZ} Output disable time from low level				40		20	40	ns

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.



SN65LBC176A, SN75LBC176A DIFFERENTIAL BUS TRANSCEIVERS

SLLS376D– MAY 2000 – REVISED JULY 2008

PARAMETER MEASUREMENT INFORMATION

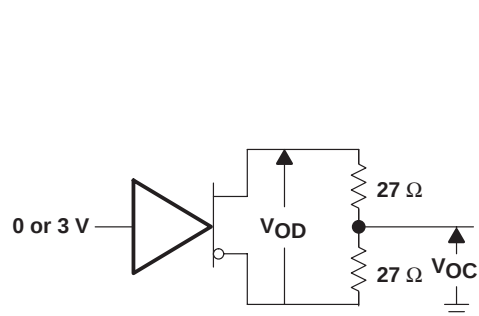
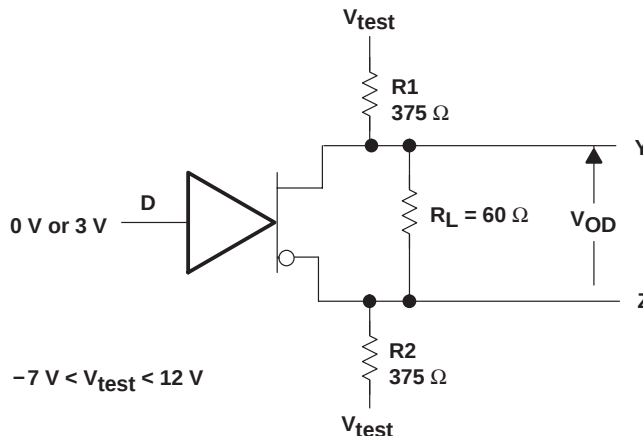
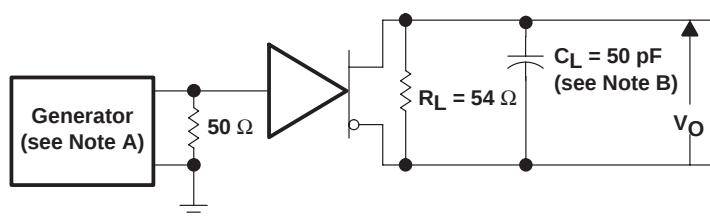


Figure 1. Driver V_{OD} and V_{OC}

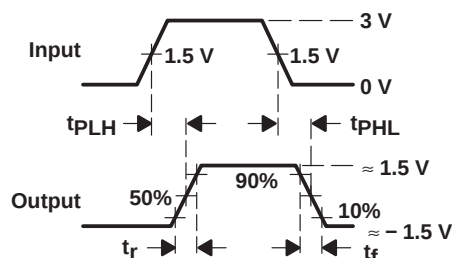


$$-7\text{ V} < V_{\text{test}} < 12\text{ V}$$

Figure 2. Driver V_{OD3}



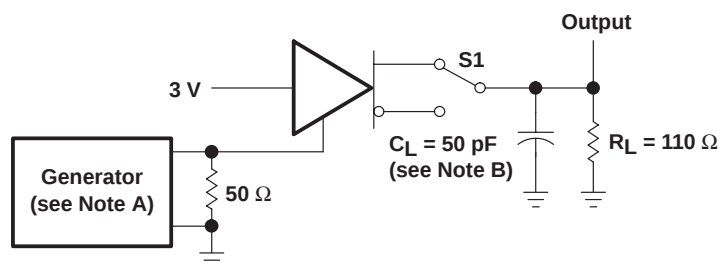
TEST CIRCUIT



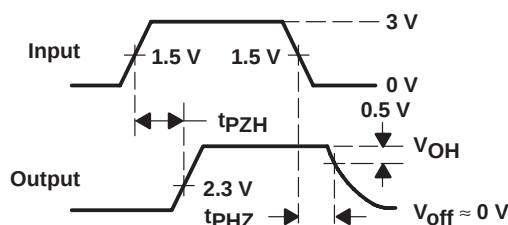
VOLTAGE WAVEFORMS

- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $\text{PRR} \leq 1\text{ MHz}$, 50% duty cycle, $t_r \leq 6\text{ ns}$, $t_f \leq 6\text{ ns}$, $Z_O = 50\ \Omega$.
B. C_L includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Voltage Waveforms



TEST CIRCUIT

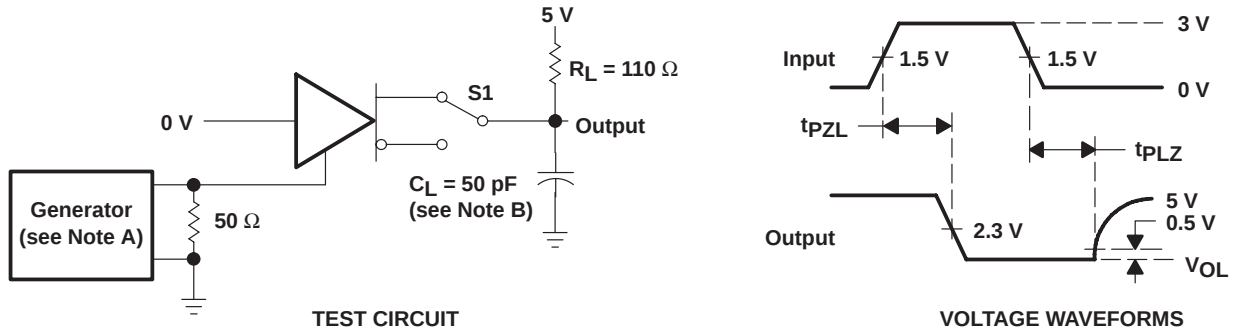


VOLTAGE WAVEFORMS

- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $\text{PRR} \leq 1\text{ MHz}$, 50% duty cycle, $t_r \leq 6\text{ ns}$, $t_f \leq 6\text{ ns}$, $Z_O = 50\ \Omega$.
B. C_L includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1$ MHz, 50% duty cycle, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$.
B. C_L includes probe and jig capacitance.

Figure 5. Driver Test Circuit and Voltage Waveforms

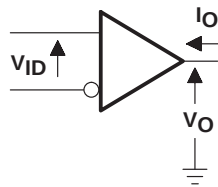
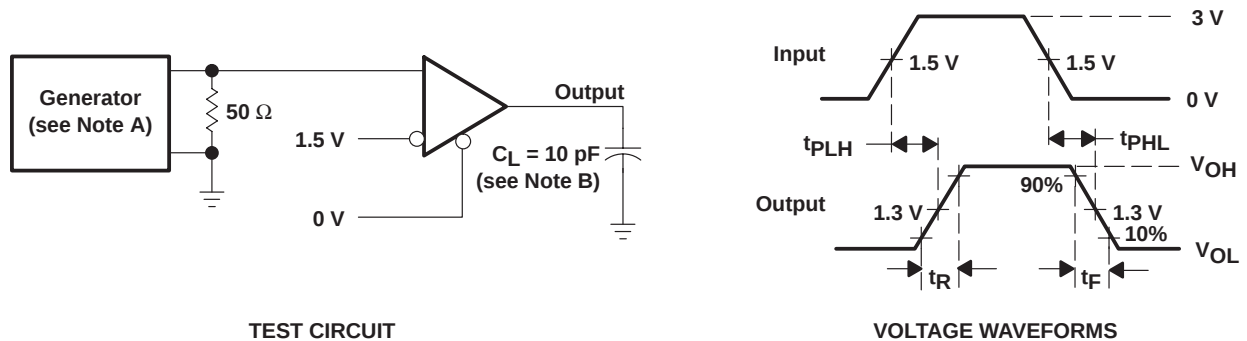


Figure 6. Receiver V_{OH} and V_{OL}



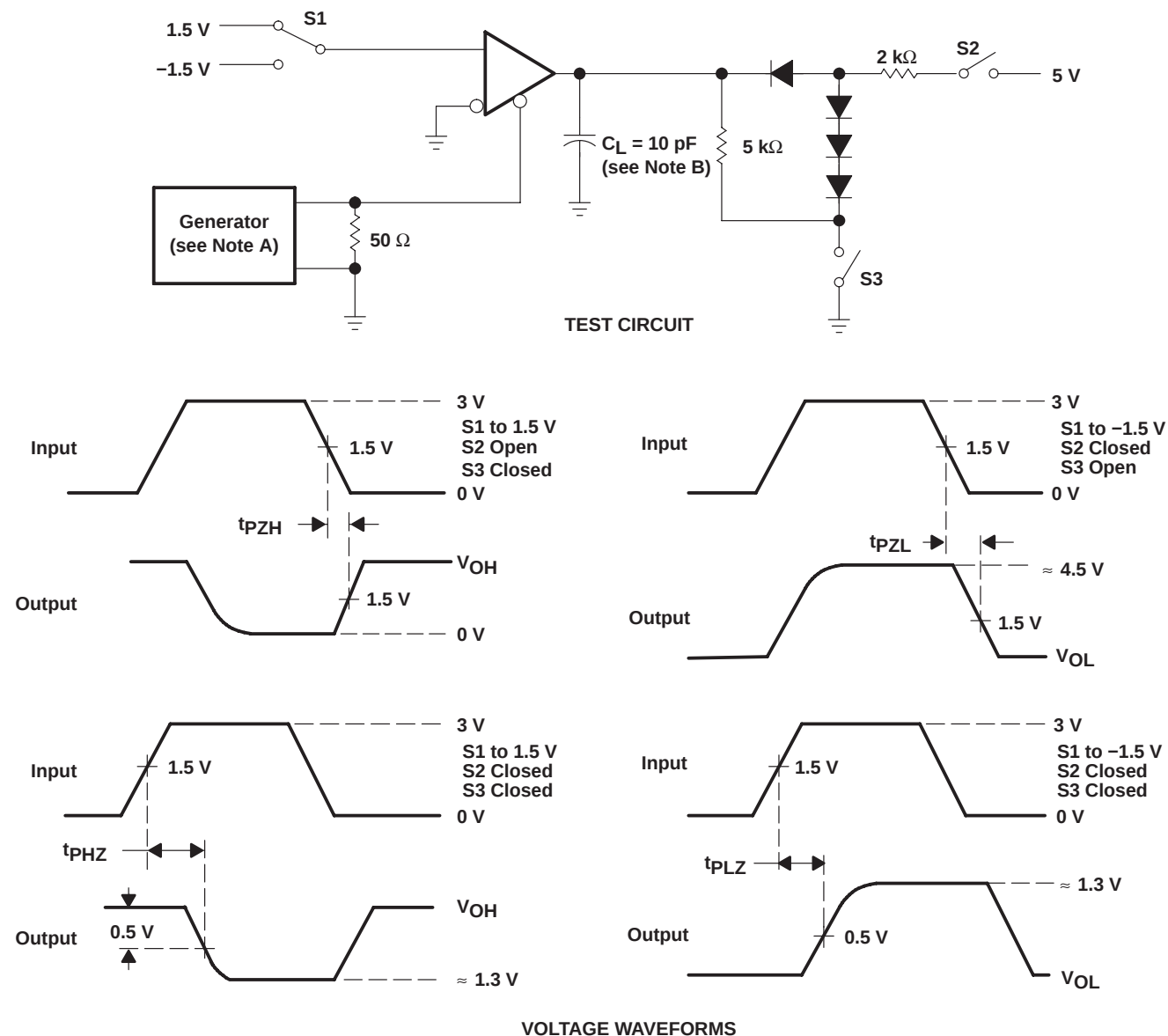
- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1$ MHz, 50% duty cycle, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$.
B. C_L includes probe and jig capacitance.

Figure 7. Receiver Test Circuit and Voltage Waveforms

SN65LBC176A, SN75LBC176A DIFFERENTIAL BUS TRANSCEIVERS

SLLS376D– MAY 2000 – REVISED JULY 2008

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR $\leq$ 1 MHz, 50% duty cycle, $t_r \leq$ 6 ns, $t_f \leq$ 6 ns, $Z_O = 50 \Omega$.
B. C_L includes probe and jig capacitance.

Figure 8. Receiver Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

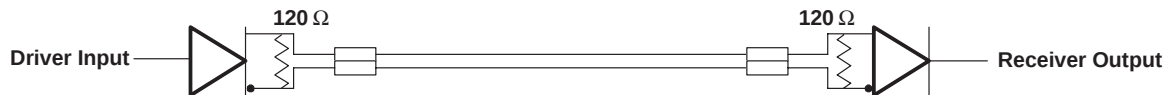
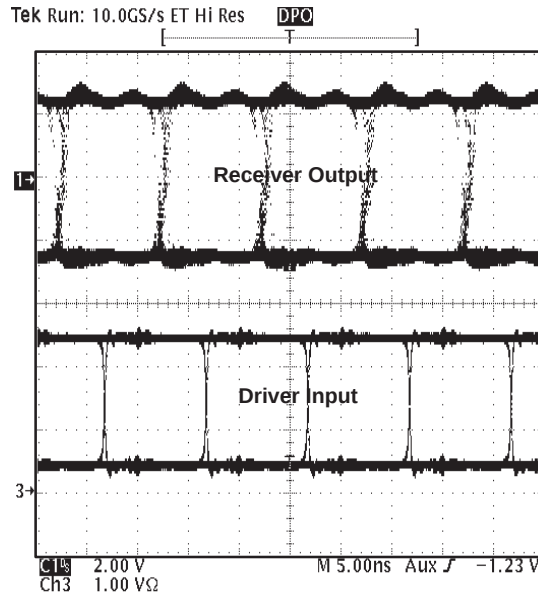


Figure 9. Typical Waveform of Non-Return-To-Zero (NRZ), Pseudorandom Binary Sequence (PRBS) Data at 100 Mbps Through 15m, of CAT 5 Unshielded Twisted Pair (UTP) Cable

TIA/EIA-485-A defines a maximum signaling rate as that in which the transition time of the voltage transition of a logic-state change remains less than or equal to 30% of the bit length. Transition times of greater length perform quite well even though they do not meet the standard definition.

SN65LBC176A, SN75LBC176A
DIFFERENTIAL BUS TRANSCEIVERS

SLLS376D- MAY 2000 - REVISED JULY 2008

TYPICAL CHARACTERISTICS

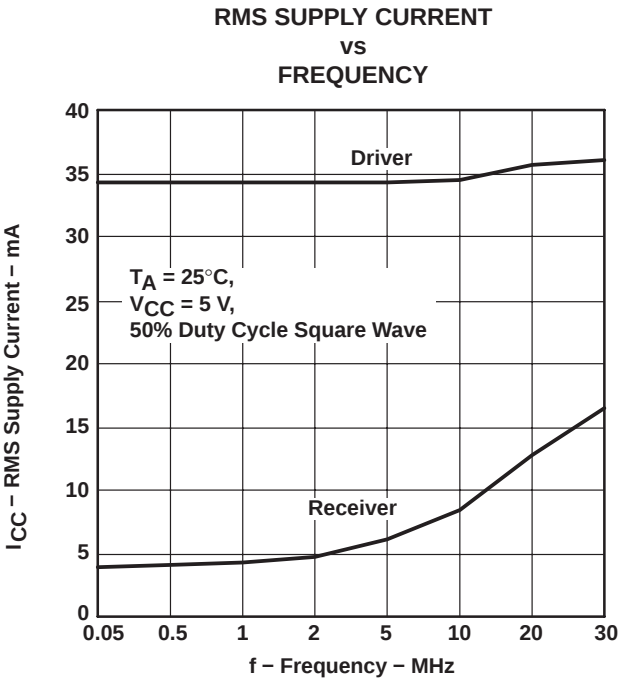


Figure 10

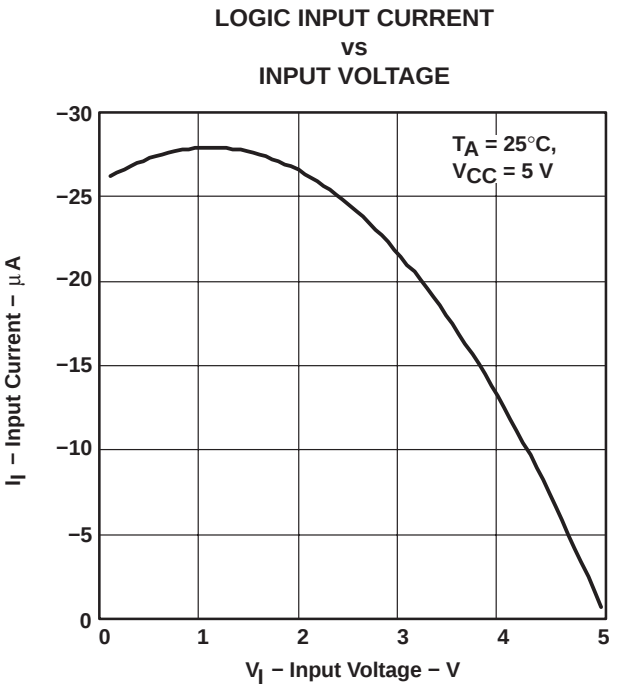


Figure 11

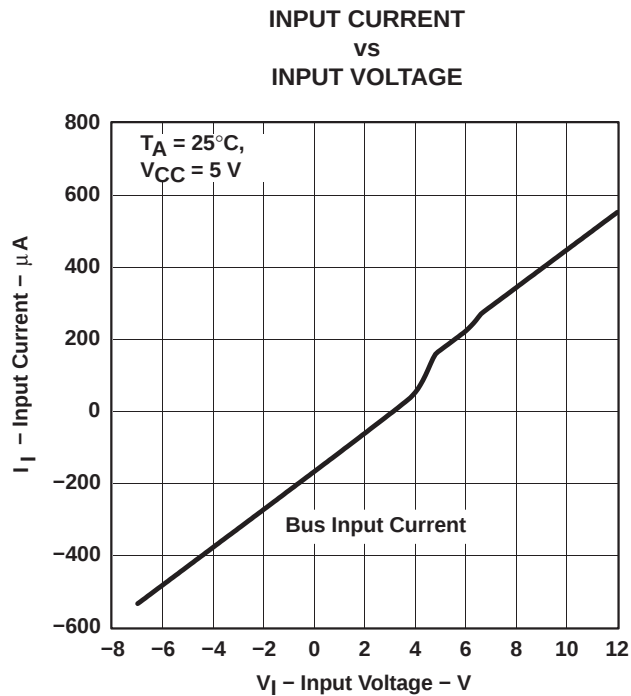


Figure 12

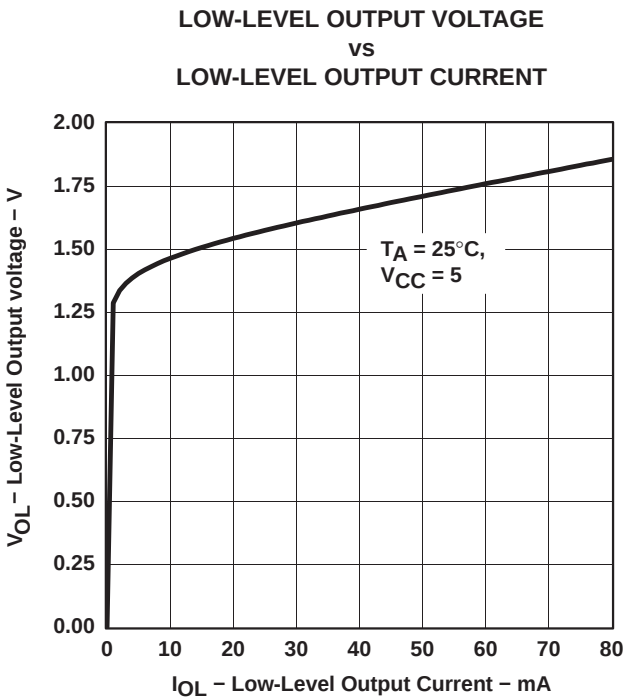


Figure 13

TYPICAL CHARACTERISTICS

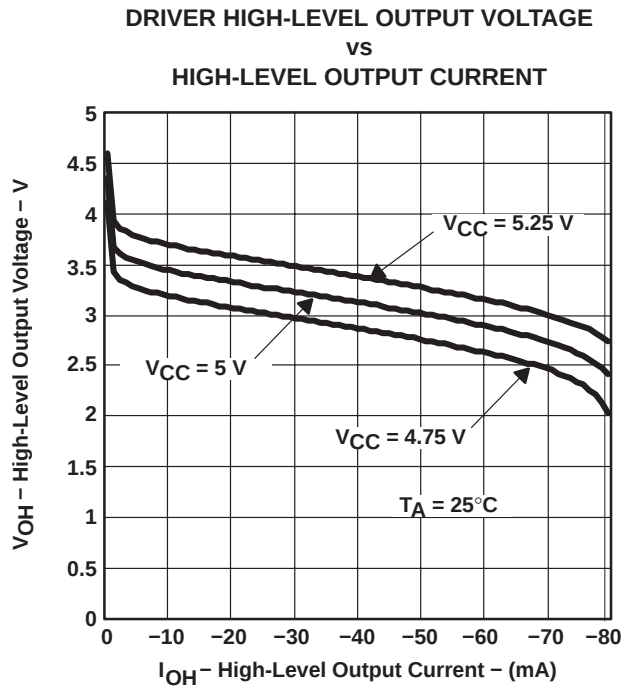


Figure 14

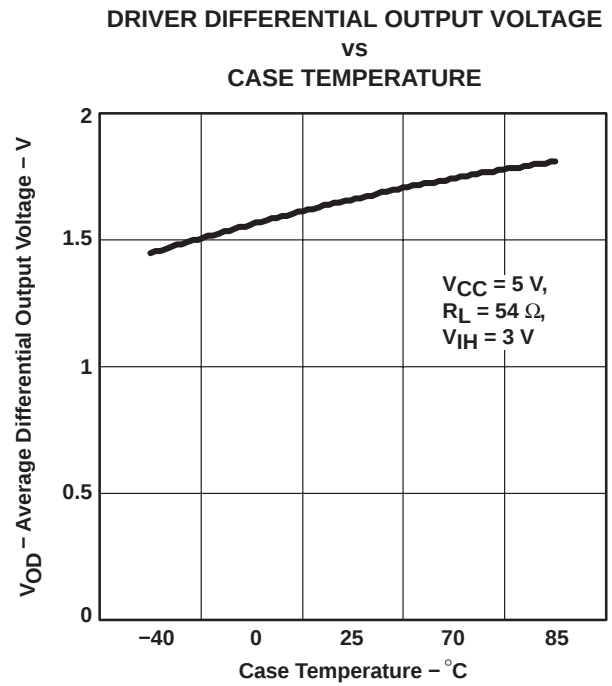


Figure 15

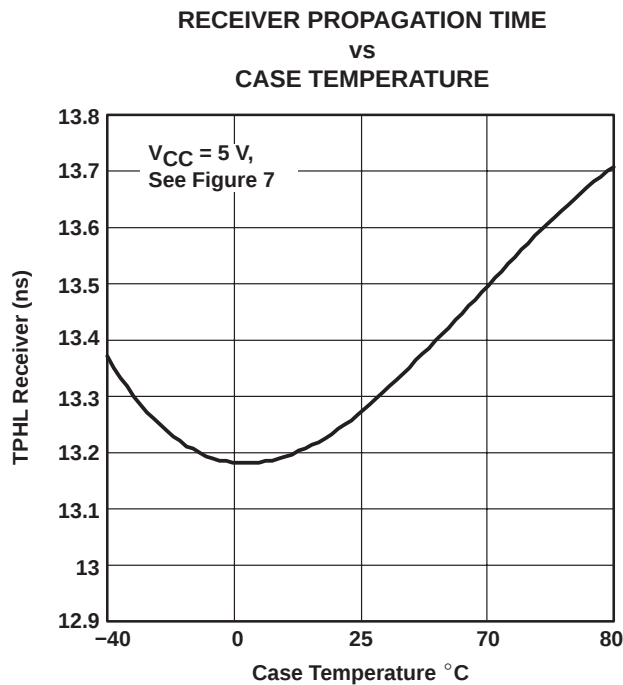


Figure 16

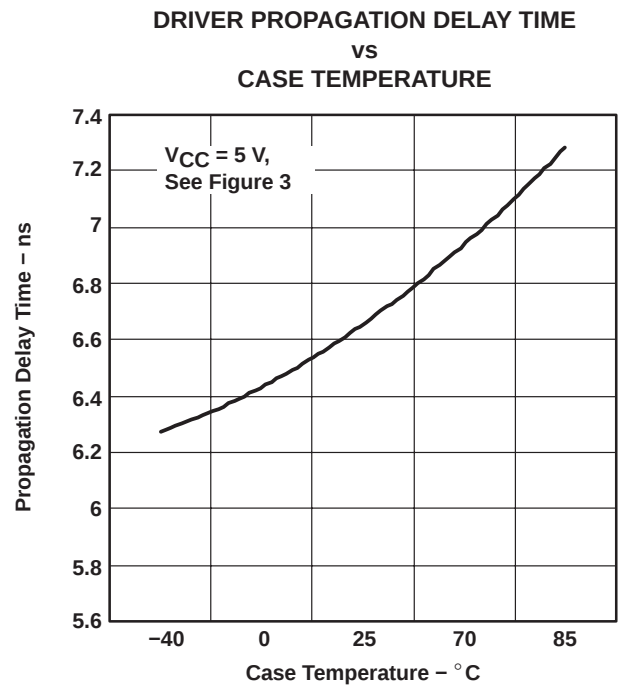


Figure 17

SN65LBC176A, SN75LBC176A
DIFFERENTIAL BUS TRANSCEIVERS

SLLS376D- MAY 2000 - REVISED JULY 2008

TYPICAL CHARACTERISTICS

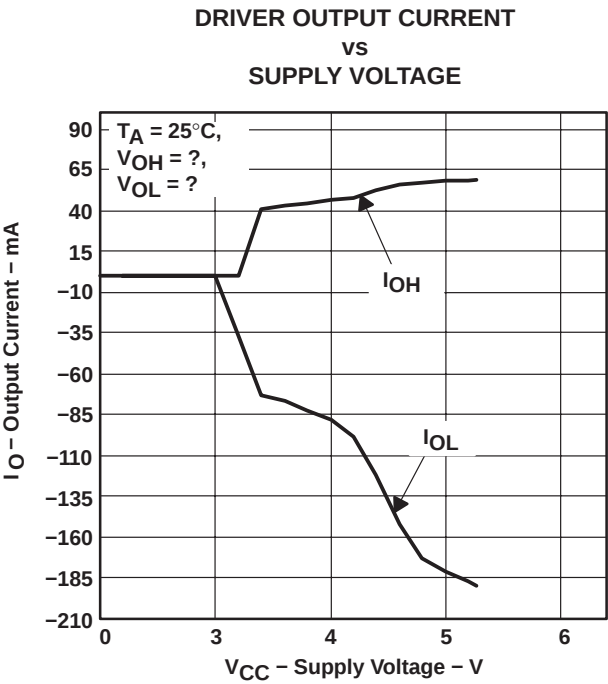


Figure 18

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN65LBC176AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN65LBC176ADG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN65LBC176ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN65LBC176ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN65LBC176AP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN65LBC176APE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN65LBC176AQD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN65LBC176AQDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN65LBC176AQDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN65LBC176AQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75LBC176AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75LBC176ADG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75LBC176ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75LBC176ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75LBC176AP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75LBC176APE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN65LBC176A :

- Enhanced Product: [SN65LBC176A-EP](#)

NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LBC176ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN65LBC176AQDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75LBC176ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LBC176ADR	SOIC	D	8	2500	340.5	338.1	20.6
SN65LBC176AQDR	SOIC	D	8	2500	340.5	338.1	20.6
SN75LBC176ADR	SOIC	D	8	2500	340.5	338.1	20.6

P (R-PDIP-T8)

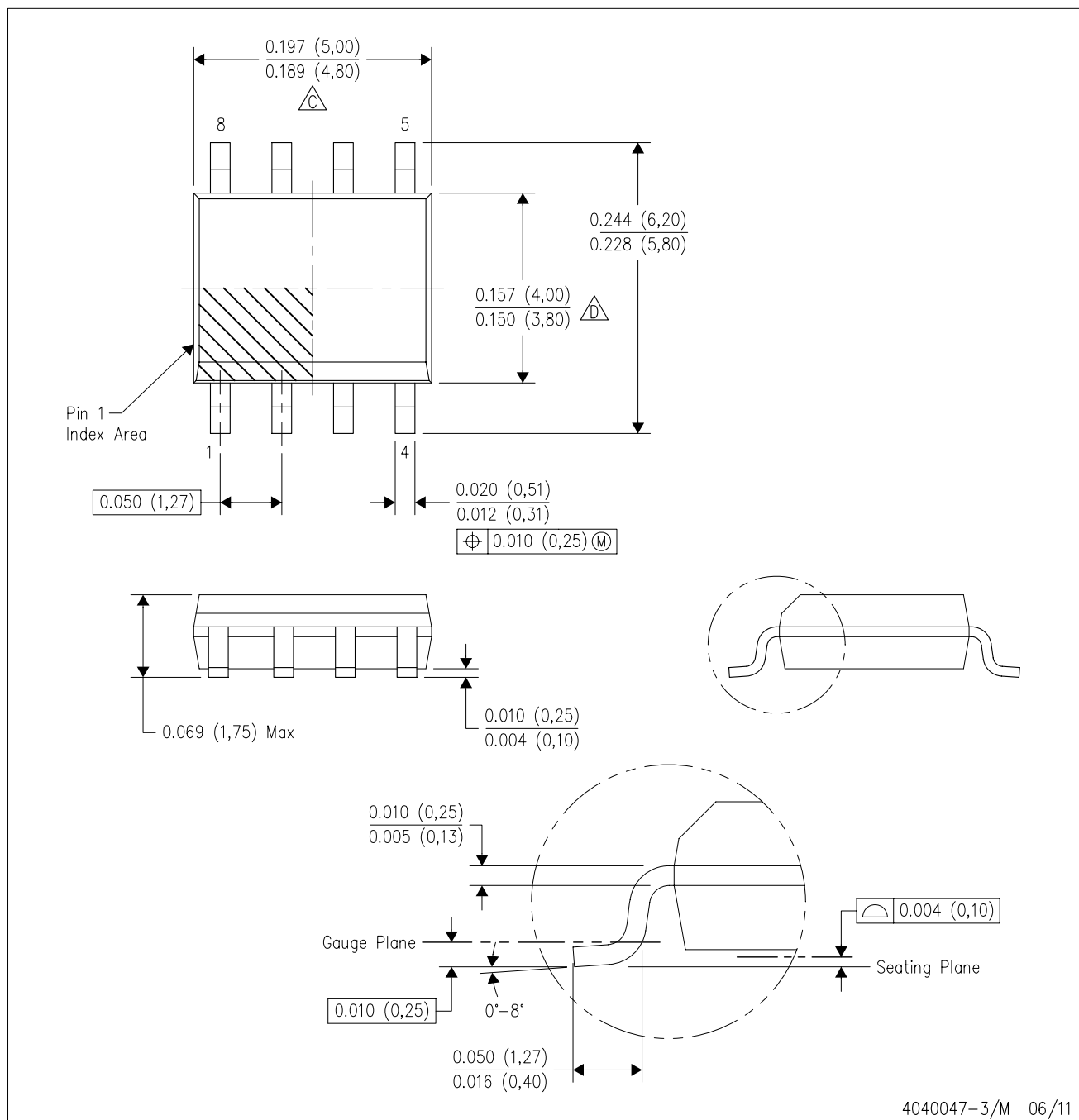
PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community e2e.ti.com



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.